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<input type="checkbox"/> DIVISIONAL APP'N	<input checked="" type="checkbox"/> REPLY BRIEF
NAME OF INVENTOR(S): Yew	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/612,129 Filing Date: 7/2/2003	
TITLE OF INVENTION: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC SUBSTRATE	
TI FILE NO.: TI-26239.1	DEPOSIT ACCT. NO.: 20-0668
FAXED: 6-8-05 DUE: 06/19/2005 ATTY/SECY: WDS/ltc	

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Applicant: Yew

Docket No: TI-26239.1

Serial No: 10/612,129

Examiner: Cao, Phat X.

Filed: 7/2/2003

Art Unit: 2814

For: DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC
SUBSTRATE

JUN 08 2005

REPLY BRIEFAssistant Commissioner For Patents
Washington, DC 20231CERTIFICATION OF FACSIMILE TRANSMISSIONI hereby certify that the following papers are being
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Tommie Chambers

Dear Sir:

Responsive to the Examiner's Answer mailed April 19, 2005 in connection with
the above identified application, Applicants respectfully submit the following remarks.

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REMARKS

The Examiner alleges on the paragraph bridging pages 7 and 8, the Appellant's arguments have no immediate apparent relevance to the issues presented by the rejection since Appellants cannot show nonobviousness by attacking references individually where the rejection is based upon the combination of references.

Appellants respectfully disagree.

Appellants have shown that both Lee and Lupinski does not disclose or suggest the presently claimed invention including a plurality of contact pads disposed on the first surface of the substrate and the second surface of the substrate being directly attached to the preactivated polymer layer.

Since both of these references do not disclose the above mentioned claimed subject matter, the combination of these references cannot disclose this subject matter and consequently the Examiner's rejection under 35 U.S.C. § 103 is improper.

Additionally, Appellants note that the Examiner has incorrectly listed the reference to Horoshi as 06-629454 and Appellants believe that it should be 06-029454.

Again for the forgoing reasons, Appellants respectfully submit that the Examiner's rejections are improper and requests the Honorable Board to reverse the Examiner's rejections.

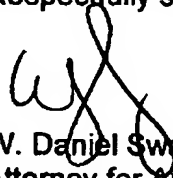
In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant response places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is

respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



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